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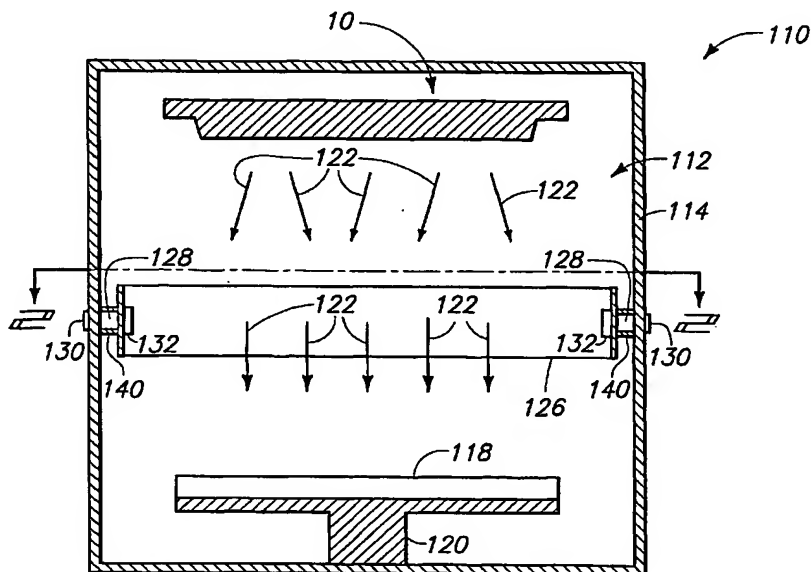
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[Continued on next page]

(54) Title: METHODS OF TREATING DEPOSITION PROCESS COMPONENTS TO FORM PARTICLE TRAPS, AND DEPOSITION PROCESS COMPONENTS HAVING PARTICLE TRAPS THEREON



(57) Abstract: The invention includes methods for forming particle traps along surfaces of PVD components, and comprises PVD components having particle traps thereon. The invention can include utilization of highly soluble media for bead-blasting and/or can include utilization of metallic materials as bead-blasting media. The invention can also include formation of an insert along regions of a backing plate where particle traps are desired, with the insert being of a composition which has better particle-trapping properties than the backing plate.



SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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